

Desoldering braid

Soder-Wick®

Soder-Wick®, global leading brand of desoldering braid, is the fastest, cleanest and safest braid in the industry. Designed for modern heat-sensitive electronic components, Soder-Wick® features a pure copper braid structure and a lighter mass that allows good thermal conductivity, even at low temperatures. The precise weaving design allows maximum capillary action and solder capacity in electronics maintenance or repair.

The Soder-Wick® desoldering braid optimises heat transfer through the braid and into the solder joint. Minimal flux residues on the board accelerate the cleaning process, or eliminate it entirely: this means little or no post-weld cleaning, no corrosive residue left.

Soder-Wick® Lead-Free

Soder-Wick Lead-Free is the state of the art in desoldering technology. It is specially designed for removal of today's high temperature lead-free solders. The single layer weave used for Soder-Wick Lead-Free braid is lighter in mass than any other desoldering braid available and allows for lead-free solder removal at lower temperatures. Soder-Wick Lead-Free responds faster than any other conventional desoldering braid

- » Fastest wicking and heat transfer
- » High capacity for solder uptake
- » Halide free, no corrosive residues
- » Minimizes risk of heat damage to pads, components and PBCs
- » Can be used with Tin/Lead solders
- » RoHS compliant



40-005-01

SODER-WICK 40-1-5 | 0,8mm/1,5mt



40-005-02

SODER-WICK 40-2-5 | 1,5mm/1,5mt



40-005-03

SODER-WICK 40-3-5 | 2,0mm/1,5mt



40-005-04

SODER-WICK 40-4-5 | 2,8mm/1,5mt

Soder-Wick® No Clean

Soder-Wick No Clean is designed to provide fast and safe desoldering without leaving behind harmful flux residues.

Soder-Wick No Clean uses pure, oxygen free copper braid and a patented flux technology to make an efficient and effective desoldering braid. Soder-Wick No Clean SD is available on ESD safe bobbins for protection against damage due to static electricity

- » Requires little or no post solder cleaning
- » No corrosive residues
- » Halide free
- » ESD Safe bobbins meet specs:
MIL-STD-1686C
MIL-HDBK-263B
- » Static decay provision of MIL-B-81705C
- » Minimal risk of heat and static component damage



60-005-01
SODER-WICK 60-1-5 | 0,8mm/1,5mt



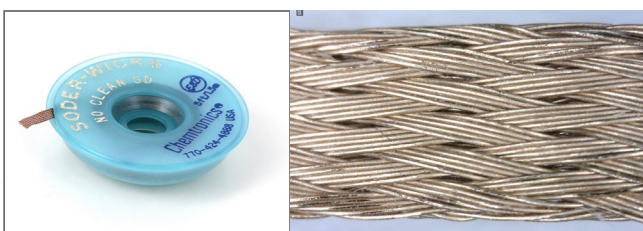
60-005-02
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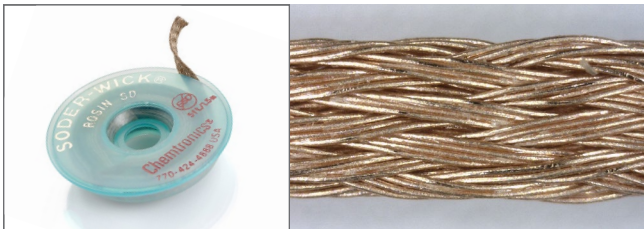


60-005-05
SODER-WICK 60-5-5 | 3,7mm/1,5mt

Soder-Wick® Rosin Flux

Soder-Wick offers the state of the art in desoldering technology. Soder-Wick is designed for today's heat sensitive electronic components using lighter mass, pure copper braid construction that allows for better thermal conductivity, even at low temperatures.

- » Soder-Wick responds faster than conventional desoldering braids thereby minimizing overheating and preventing PCB damage.
- » Soder-Wick Rosin has the fastest desoldering action in the industry.
- » Flux residues must be cleaned after the rework process.



50-100-02

SODER-WICK 50-2-100 | 1,5mm/30,5mt



50-100-03

SODER-WICK 50-3-100 | 2,0mm/30,5mt



50-100-04

SODER-WICK 50-4-100 | 2,8mm/30,5mt



80-005-01

SODER-WICK 80-1-5 | 0,8mm/1,5mt



80-005-02

SODER-WICK 80-2-5 | 1,5mm/1,5mt



80-005-03

SODER-WICK 80-3-5 | 2,0mm/1,5mt



80-005-04
SODER-WICK 80-4-5 | 2,8mm/1,5mt



80-005-05
SODER-WICK 80-5-5 | 3,7mm/1,5mt



80-005-06
SODER-WICK 80-6-5 | 3mm/1,5mt



80-BGA-5-5
SODER-WICK 80-BGA-5 | 1,5mt